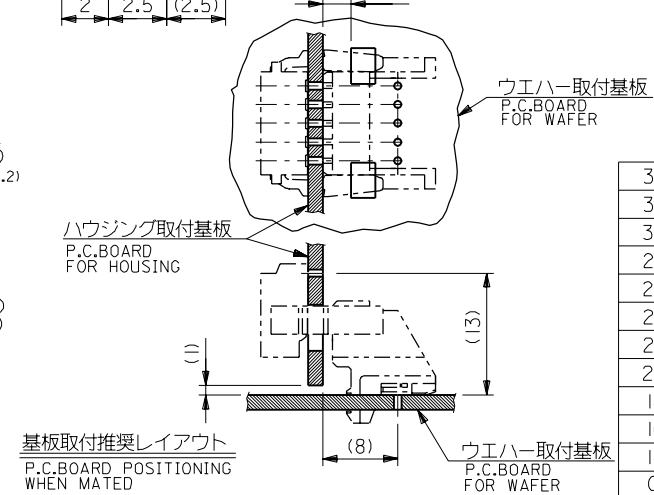
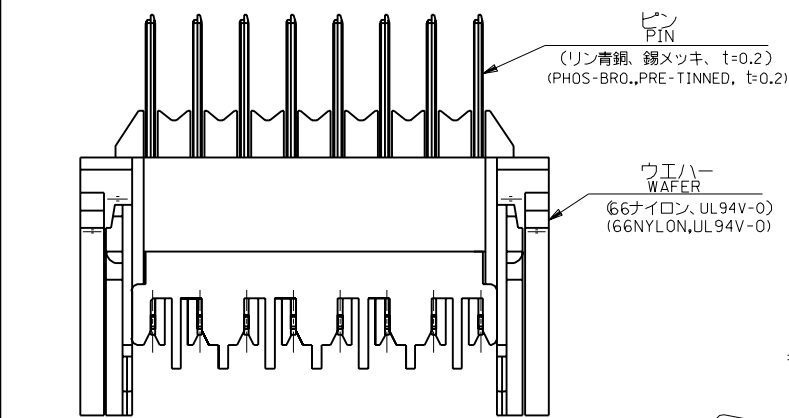


基板取付穴推奨寸法 (マウント面) (基板厚: 1.6)  
 RECOMMENDED P.C. BOARD HOLE DIM.  
 (MOUNT SURFACE) (t=1.6)

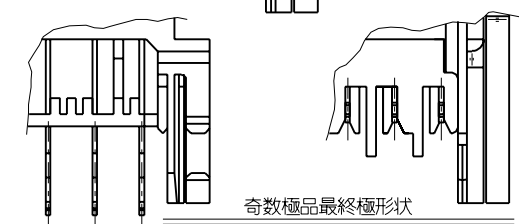
注記  
NOTE

1. 嵌合相手: 52170-\*\*\*10  
 MATE WITH 52170-\*\*\*10



基板取付推奨レイアウト  
 P.C. BOARD POSITIONING  
 WHEN MATED

34	31	28	53114-1510	15
32	29	26	-1410	14
30	27	24	-1310	13
28	25	22	-1210	12
26	23	20	-1110	11
24	21	18	-1010	10
22	19	16	-0910	9
20	17	14	-0810	8
18	15	12	-0710	7
16	13	10	-0610	6
14	11	8	53114-0510	5
C	B	A	ENG. NO.	極数 CKT.



THE LAST CKT VIEW OF ODD CKT CONN.

角度 ANGLE	±3°
30以上 OVER	+0.3
10以上 30未満 UNDER	+0.25
10未満 UNDER	+0.2
記号 LTR	変更内容 REVISION RECORD
DR. CHK.	DATE

材料 MATERIAL	図中参照 SEE DRAWING
仕上げ FINISH	— / —
適用電線範囲 WIRE RANGE	— / —
被覆外径 INS. RANGE	— / —
DRAWN BY '95/09/11	CHK'D BY '95/09/11
S.MATSUZAKI	M.H.HIRAMOTO
APP'D BY '95/09/11	尺度 SCALE 5 : 1
M.FUKUSHIMA	

molex MOLEX-JAPAN CO.,LTD. 日本モレックス株式会社	
REVISE ONLY ON CAD SYSTEM	
TITLE 名称 2.0 FLOATING BOARD TO BOARD CONN. WAFER ASS'Y	
DWG. NO. SD-53114-***10	REV C